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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	16MHz
Connectivity	CANbus, I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, Voltage Detect, WDT
Number of I/O	41
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21236kfp-u1

1.4 Product Information

Table 1.3 lists Product Information for R8C/22 Group and Table 1.4 lists Product Information for R8C/23 Group.

Table 1.3 Product Information for R8C/22 Group

Current of Aug. 2008

Type No.	ROM Capacity	RAM Capacity	Package Type	Remarks	
R5F21226DFP	32 Kbytes	2 Kbytes	PLQP0048KB-A	D version	Flash memory version
R5F21227DFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21228DFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F21226JFP	32 Kbytes	2 Kbytes	PLQP0048KB-A	J version	
R5F21227JFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21228JFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F2122AJFP	96 Kbytes	5 Kbytes	PLQP0048KB-A	K version	
R5F2122CJFP	128 Kbytes ⁽¹⁾	6 Kbytes	PLQP0048KB-A		
R5F21226KFP	32 Kbytes	2 Kbytes	PLQP0048KB-A		
R5F21227KFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21228KFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F2122AKFP	96 Kbytes	5 Kbytes	PLQP0048KB-A		
R5F2122CKFP	128 Kbytes ⁽¹⁾	6 Kbytes	PLQP0048KB-A		

NOTE:

- Do not use addresses 20000h to 23FFFh because these areas are used for the emulator debugger. Refer to **24. Notes on Emulator Debugger** of Hardware Manual.

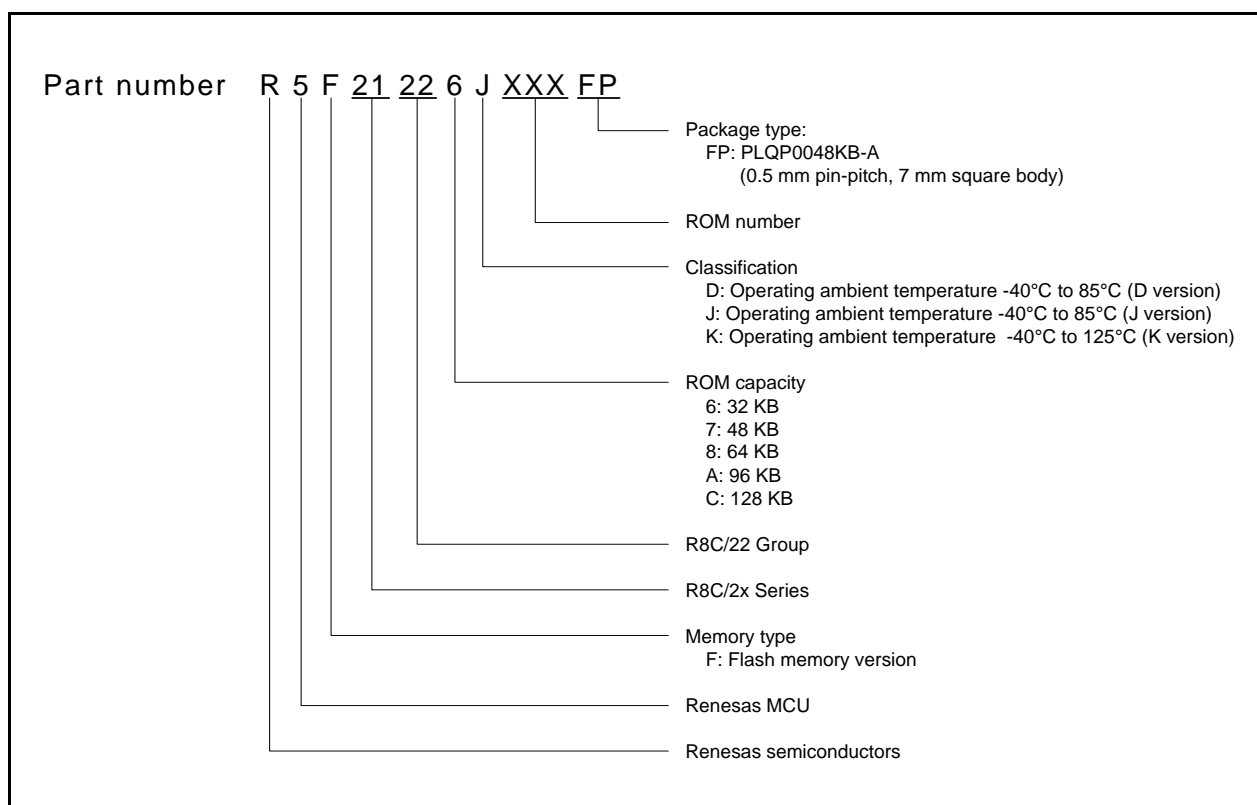


Figure 1.2 Type Number, Memory Size, and Package of R8C/22 Group

Table 1.4 Product Information for R8C/23 Group

Current of Aug. 2008

Type No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data Flash				
R5F21236DFP	32 Kbytes	1 Kbyte X 2	2 Kbytes	PLQP0048KB-A	D version	Flash memory version
R5F21237DFP	48 Kbytes	1 Kbyte X 2	2.5 Kbytes	PLQP0048KB-A		
R5F21238DFP	64 Kbytes	1 Kbyte X 2	3 Kbytes	PLQP0048KB-A		
R5F21236JFP	32 Kbytes	1 Kbyte X 2	2 Kbytes	PLQP0048KB-A	J version	
R5F21237JFP	48 Kbytes	1 Kbyte X 2	2.5 Kbytes	PLQP0048KB-A		
R5F21238JFP	64 Kbytes	1 Kbyte X 2	3 Kbytes	PLQP0048KB-A		
R5F2123AJFP	96 Kbytes	1 Kbyte X 2	5 Kbytes	PLQP0048KB-A	K version	
R5F2123CJFP	128 Kbytes ⁽¹⁾	1 Kbyte X 2	6 Kbytes	PLQP0048KB-A		
R5F21236KFP	32 Kbytes	1 Kbyte X 2	2 Kbytes	PLQP0048KB-A		
R5F21237KFP	48 Kbytes	1 Kbyte X 2	2.5 Kbytes	PLQP0048KB-A		
R5F21238KFP	64 Kbytes	1 Kbyte X 2	3 Kbytes	PLQP0048KB-A		
R5F2123AKFP	96 Kbytes	1 Kbyte X 2	5 Kbytes	PLQP0048KB-A		
R5F2123CKFP	128 Kbytes ⁽¹⁾	1 Kbyte X 2	6 Kbytes	PLQP0048KB-A		

NOTE:

- Do not use addresses 20000h to 23FFFh because these areas are used for the emulator debugger. Refer to **24. Notes on Emulator Debugger** of Hardware Manual.

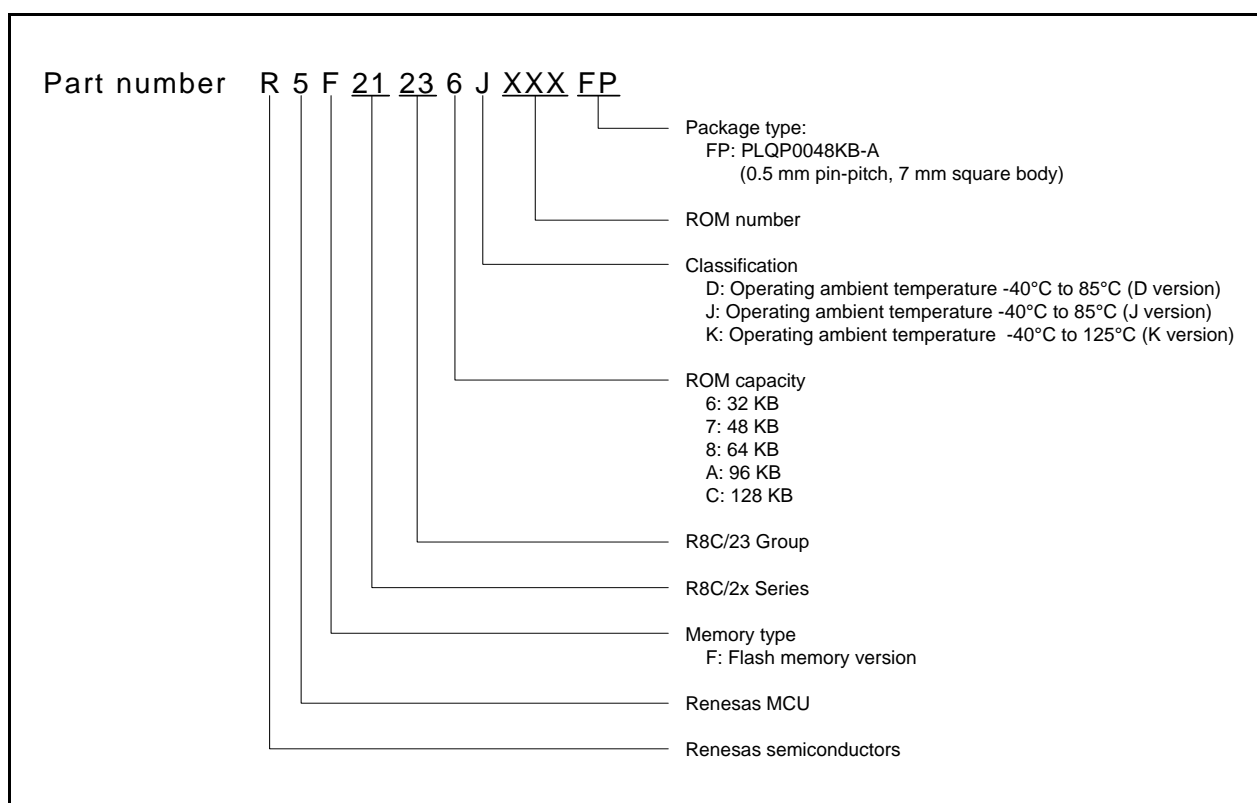


Figure 1.3 Type Number, Memory Size, and Package of R8C/23 Group

1.6 Pin Functions

Table 1.5 lists the Pin Functions and Table 1.6 lists the Pin Name Information by Pin Number.

Table 1.5 Pin Functions

Type	Symbol	I/O Type	Description
Power Supply Input	VCC VSS	I	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog Power Supply Input	AVCC, AVSS	I	Applies the power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset Input	$\overline{\text{RESET}}$	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN Clock Input	XIN	I	These pins are provided for the XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
XIN Clock Output	XOUT	O	
$\overline{\text{INT}}$ Interrupt Input	$\overline{\text{INT0}}$ to $\overline{\text{INT3}}$	I	$\overline{\text{INT}}$ interrupt input pins. $\overline{\text{INT0}}$ Timer RD input pins. $\overline{\text{INT1}}$ Timer RA input pins.
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins.
Timer RA	TRAIO	I/O	Timer RA I/O pin.
	TRA0	O	Timer RA output pin.
Timer RB	TRBO	O	Timer RB output pin.
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDI0C0, TRDI0C1, TRDI0D0, TRDI0D1	I/O	Timer RD I/O ports.
	TRDCLK	I	External clock input pin.
Timer RE	TREO	O	Divided clock output pin.
Serial Interface	CLK0	I/O	Transfer clock I/O pin.
	RXD0, RXD1	I	Serial data input pins.
	TXD0, TXD1	O	Serial data output pins.
I ² C Bus Interface	SCL	I/O	Clock I/O pin.
	SDA	I/O	Data I/O pin.
Clock Synchronous Serial I/O with Chip Select	SSI	I/O	Data I/O pin.
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin.
	SSCK	I/O	Clock I/O pin.
	SSO	I/O	Data I/O pin.
CAN Module	CRX0	I	CAN data input pin.
	CTX0	O	CAN data output pin.
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter.
A/D Converter	AN0 to AN11	I	Analog input pins to A/D converter.
I/O Port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6_0 to P6_7	I/O	CMOS I/O ports. Each port contains an input/output select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by a program.
Input Port	P4_2, P4_6, P4_7	I	Input only ports.

I: Input O: Output I/O: Input and output

2.8.7 Interrupt Enable Flag (I)

The I flag enables a maskable interrupt.

An interrupt is disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers. 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has greater priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/22 Group

Figure 3.1 shows a Memory Map of R8C/22 Group. The R8C/22 Group has 1 Mbyte of address space from address 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFR) are allocated addresses 00000h to 002FFh and 01300h to 0147Fh (SFR area for CAN). The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future user and cannot be accessed by users.

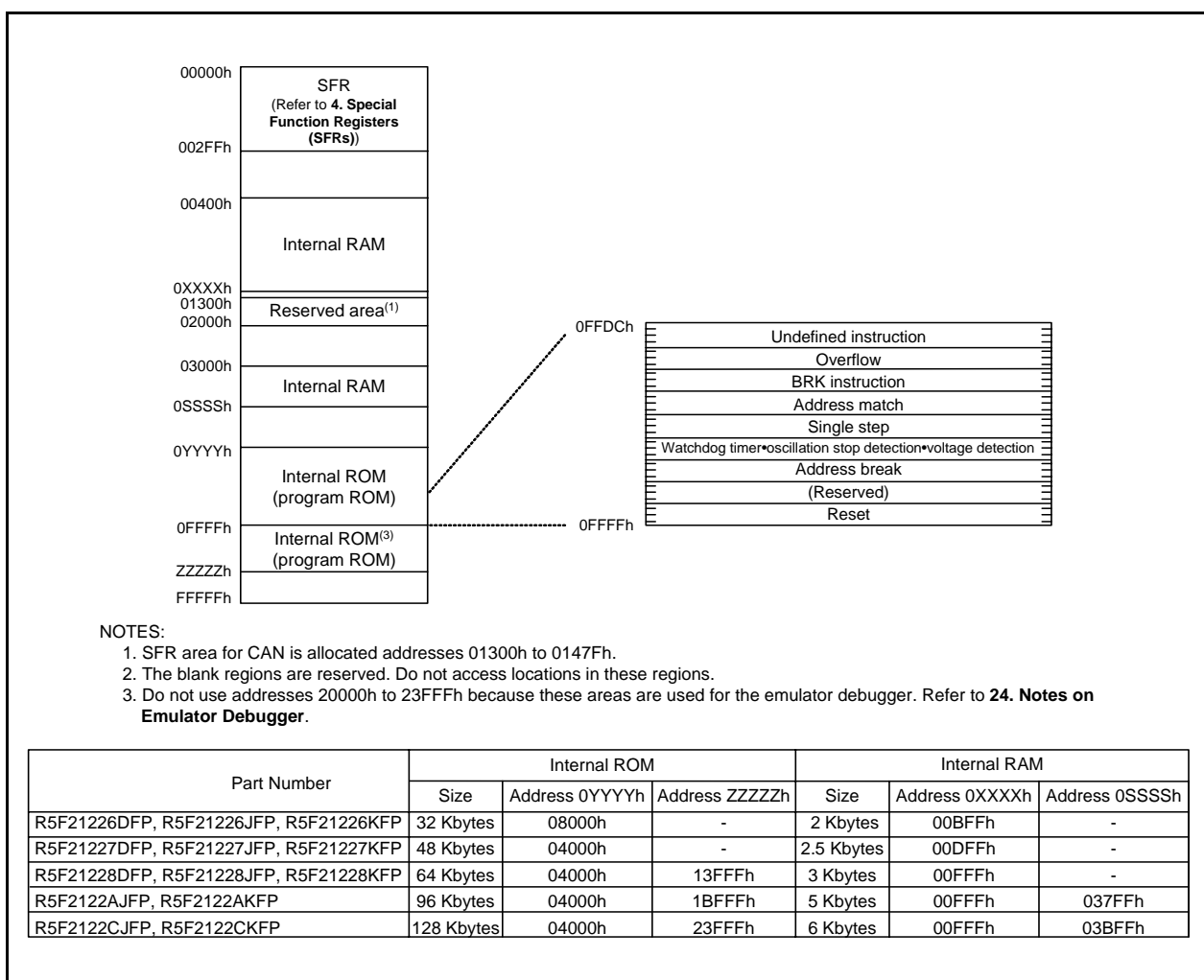


Figure 3.1 Memory Map of R8C/22 Group

3.2 R8C/23 Group

Figure 3.2 shows a Memory Map of R8C/23 Group. The R8C/23 Group has 1 Mbyte of address space from address 00000h to FFFFFFFh.

The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFR) are allocated addresses 00000h to 002FFh and 01300h to 0147Fh (SFR area for CAN). The peripheral function control registers are allocated them. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

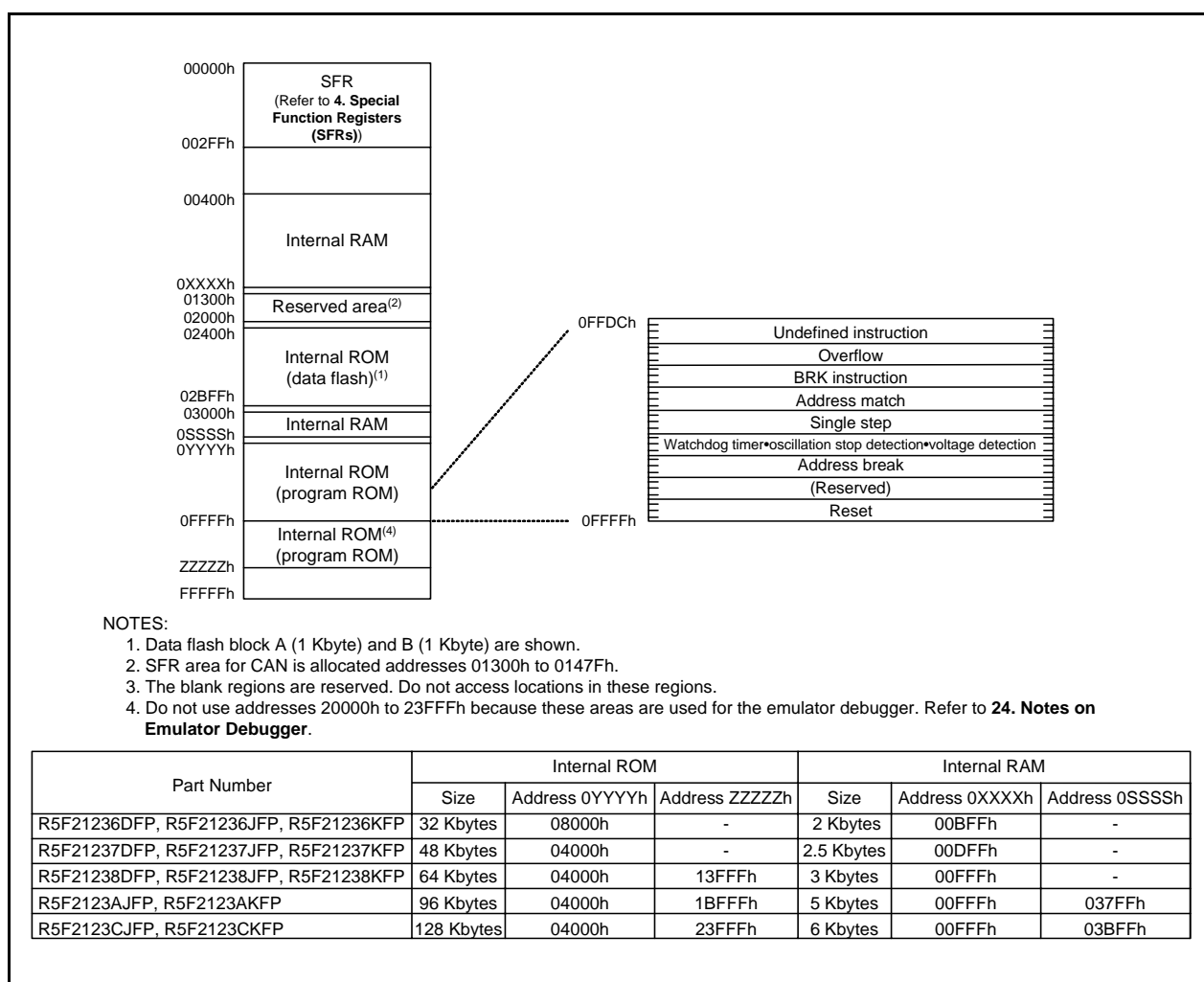


Figure 3.2 Memory Map of R8C/23 Group

Table 4.2 SFR Information (2)⁽¹⁾

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h	CAN0 Wake Up Interrupt Control Register	C01WKIC	XXXXX000b
0044h	CAN0 Successful Reception Interrupt Control Register	C0RECIC	XXXXX000b
0045h	CAN0 Successful Transmission Interrupt Control Register	C0TRMIC	XXXXX000b
0046h	CAN0 State/Error Interrupt Control Register	C01ERRIC	XXXXX000b
0047h			
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register/IIC Bus Interrupt Control Register ⁽²⁾	SSUIC/IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.4 SFR Information (4)⁽¹⁾

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h	UART1 Function Select Register	U1SR	XXh
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	XX00XX00b
00FEh			
00FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.5 SFR Information (5)⁽¹⁾

Address	Register	Symbol	After reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h			
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRES	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Counter Data Register	TRESEC	00h
0119h	Timer RE Compare Data Register	TREMIN	00h
011Ah			
011Bh			
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Count Source Select Register	TRECSR	00001000b
011Fh			
0120h			
0121h			
0122h			
0123h			
0124h			
0125h			
0126h			
0127h			
0128h			
0129h			
012Ah			
012Bh			
012Ch			
012Dh			
012Eh			
012Fh			
0130h			
0131h			
0132h			
0133h			
0134h			
0135h			
0136h			
0137h	Timer RD Start Register	TRDSTR	11111100b
0138h	Timer RD Mode Register	TRDMR	00001110b
0139h	Timer RD PWM Mode Register	TRDPMR	10001000b
013Ah	Timer RD Function Control Register	TRDFCR	10000000b
013Bh	Timer RD Output Master Enable Register 1	TRDOER1	FFh
013Ch	Timer RD Output Master Enable Register 2	TRDOER2	01111111b
013Dh	Timer RD Output Control Register	TRDOCR	00h
013Eh	Timer RD Digital Filter Function Select Register 0	TRDDF0	00h
013Fh	Timer RD Digital Filter Function Select Register 1	TRDDF1	00h

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.6 SFR Information (6)⁽¹⁾

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIOA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIOA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h			
0161h			
0162h			
0163h			
0164h			
0165h			
0166h			
0167h			
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.7 SFR Information (7)⁽¹⁾

Address	Register	Symbol	After reset
0180h			
0181h			
0182h			
0183h			
0184h			
0185h			
0186h			
0187h			
0188h			
0189h			
018Ah			
018Bh			
018Ch			
018Dh			
018Eh			
018Fh			
0190h			
0191h			
0192h			
0193h			
0194h			
0195h			
0196h			
0197h			
0198h			
0199h			
019Ah			
019Bh			
019Ch			
019Dh			
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h			
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01FDh			
01FEh			
01FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.10 SFR Information (10)⁽¹⁾

Address	Register	Symbol	After reset
1380h	CAN0 Slot 2: Identifier/DLC		XXh
1381h			XXh
1382h			XXh
1383h			XXh
1384h			XXh
1385h			XXh
1386h	CAN0 Slot 2: Data Field		XXh
1387h			XXh
1388h			XXh
1389h			XXh
138Ah			XXh
138Bh			XXh
138Ch			XXh
138Dh			XXh
138Eh	CAN0 Slot 2: Time Stamp		XXh
138Fh			XXh
1390h	CAN0 Slot 3: Identifier/DLC		XXh
1391h			XXh
1392h			XXh
1393h			XXh
1394h			XXh
1395h			XXh
1396h	CAN0 Slot 3: Data Field		XXh
1397h			XXh
1398h			XXh
1399h			XXh
139Ah			XXh
139Bh			XXh
139Ch			XXh
139Dh			XXh
139Eh	CAN0 Slot 3: Time Stamp		XXh
139Fh			XXh
13A0h	CAN0 Slot 4: Identifier/DLC		XXh
13A1h			XXh
13A2h			XXh
13A3h			XXh
13A4h			XXh
13A5h			XXh
13A6h	CAN0 Slot 4: Data Field		XXh
13A7h			XXh
13A8h			XXh
13A9h			XXh
13AAh			XXh
13ABh			XXh
13ACh			XXh
13ADh			XXh
13AEh	CAN0 Slot 4: Time Stamp		XXh
13AFh			XXh
13B0h	CAN0 Slot 5: Identifier/DLC		XXh
13B1h			XXh
13B2h			XXh
13B3h			XXh
13B4h			XXh
13B5h			XXh
13B6h	CAN0 Slot 5: Data Field		XXh
13B7h			XXh
13B8h			XXh
13B9h			XXh
13BAh			XXh
13BBh			XXh
13BCh			XXh
13BDh			XXh
13BEh	CAN0 Slot 5: Time Stamp		XXh
13BFh			XXh

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated value	Unit
V _{CC} /AV _{CC}	Supply voltage		-0.3 to 6.5	V
V _I	Input voltage		-0.3 to V _{CC} +0.3	V
V _O	Output voltage		-0.3 to V _{CC} +0.3	V
P _d	Power dissipation	-40°C ≤ Topr ≤ 85°C	300	mW
		85°C < Topr ≤ 125°C	125	mW
Topr	Operating ambient temperature		-40 to 85 (D, J version) / -40 to 125 (K version)	°C
T _{stg}	Storage temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage			2.7	—	5.5	V
V _{SS} /AV _{SS}	Supply voltage			—	0	—	V
V _{IH}	Input "H" voltage			0.8V _{CC}	—	V _{CC}	V
V _{IL}	Input "L" voltage			0	—	0.2V _{CC}	V
I _{OH} (sum)	Peak sum output "H" current	Sum of all Pins I _{OH} (peak)		—	—	-60	mA
I _{OH} (peak)	Peak output "H" current			—	—	-10	mA
I _{OH} (avg)	Average output "H" current			—	—	-5	mA
I _{OL} (sum)	Peak sum output "L" currents	Sum of all Pins I _{OL} (peak)		—	—	60	mA
I _{OL} (peak)	Peak output "L" currents			—	—	10	mA
I _{OL} (avg)	Average output "L" current			—	—	5	mA
f(XIN)	XIN clock input oscillation frequency		3.0 V ≤ V _{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 85°C	0	—	20	MHz
			3.0 V ≤ V _{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 125°C	0	—	16	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	—	10	MHz
—	System clock	OCD2 = 0 When XIN clock is selected.	3.0 V ≤ V _{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 85°C	0	—	20	MHz
			3.0 V ≤ V _{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 125°C	0	—	16	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	—	10	MHz
		OCD2 = 1 When on-chip oscillator clock is selected.	FRA01 = 0 When low-speed on-chip oscillator clock is selected.	—	125	—	kHz
			FRA01 = 1 When high-speed on-chip oscillator clock is selected. 3.0 V ≤ V _{CC} ≤ 5.5 V -40°C ≤ Topr ≤ 85°C	—	—	20	MHz
			FRA01 = 1 When high-speed on-chip oscillator clock is selected.	—	—	10	MHz

NOTES:

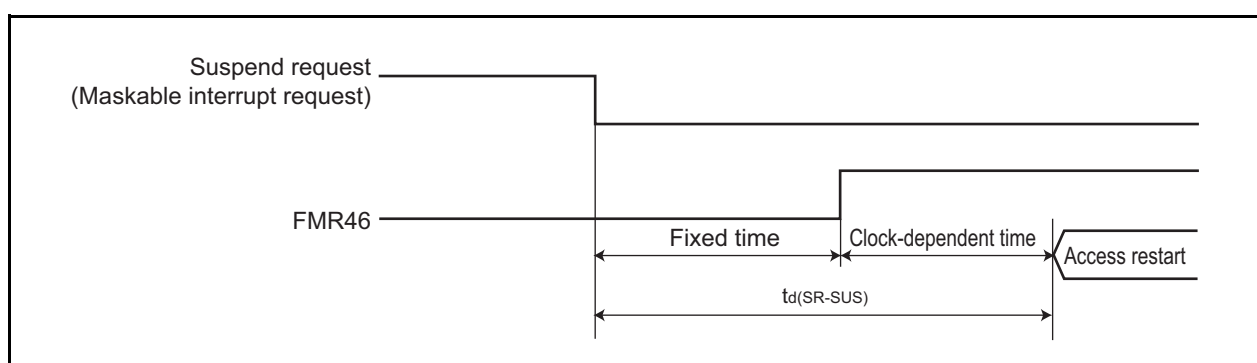
- V_{CC} = 2.7 to 5.5 V at Topr = -40 to 85°C (D, J version) / -40 to 125°C (K version), unless otherwise specified.
- The average output current indicates the average value of current measured during 100 ms.

Table 5.5 Flash Memory (Data Flash Block A, Block B) Electrical Characteristics⁽⁴⁾

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾		10,000 ⁽³⁾	–	–	times
–	Byte program time (Program/erase endurance ≤ 1,000 times)		–	50	400	μs
–	Byte program time (Program/erase endurance > 1,000 times)		–	65	–	μs
–	Block erase time (Program/erase endurance ≤ 1,000 times)		–	0.2	9	s
–	Block erase time (Program/erase endurance > 1,000 times)		–	0.3	–	s
t _d (SR-SUS)	Time delay from suspend request until erase suspend		–	–	97 + CPU clock × 6 cycle	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3 + CPU clock × 4 cycle	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		-40	–	85 ⁽⁸⁾	°C
–	Data hold time ⁽⁹⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = -40 to 85°C (D, J version) / -40 to 125°C (K version), unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 10,000), each block can be erased n times.
For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Minimum endurance to guarantee all electrical characteristics after program and erase (1 to Min. value can be guaranteed).
4. Standard of block A and block B when program and erase endurance exceeds 1,000 times. Byte program time to 1,000 times are the same as that in program ROM.
5. In a system that executes multiple programming operations, the actual erasure endurance can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A and B can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
6. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error does not occur.
7. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
8. 125°C for K version.
9. The data hold time includes time that the power supply is off or the clock is not supplied.

**Figure 5.2** Time delay until Suspend**Table 5.6** Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det1}	Voltage detection level ^(3, 4)		2.70	2.85	3.00	V
t _d (V _{det1} -A)	Voltage monitor 1 reset generation time ⁽⁵⁾		–	40	200	μs
–	Voltage detection circuit self power consumption	VCA26 = 1, V _{CC} = 5.0 V	–	0.6	–	μA
t _d (E-A)	Waiting time until voltage detection circuit operation starts ⁽²⁾		–	–	100	μs
V _{ccmin}	MCU operating voltage minimum value		2.70	–	–	V

NOTES:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and Topr = -40°C to 85°C (D, J version) / -40°C to 125°C (K version).
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.
3. Hold V_{det2} > V_{det1}.
4. This parameter shows the voltage detection level when the power supply drops. The voltage detection level when the power supply rises is higher than the voltage detection level when the power supply drops by approximately 0.1 V.
5. Time until the voltage monitor 1 reset is generated after the voltage passes V_{det1} when V_{CC} falls. When using the digital filter, its sampling time is added to t_d(V_{det1}-A). When using the voltage monitor 1 reset, maintain this time until V_{CC} = 2.0 V after the voltage passes V_{det1} when the power supply falls.

Table 5.7 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det2}	Voltage detection level ⁽⁴⁾		3.3	3.6	3.9	V
t _d (V _{det2} -A)	Voltage monitor 2 reset/interrupt request generation time ^(2, 5)		–	40	200	μs
–	Voltage detection circuit self power consumption	VCA27 = 1, V _{CC} = 5.0V	–	0.6	–	μA
t _d (E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		–	–	100	μs

NOTES:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and Topr = -40°C to 85°C (D, J version) / -40°C to 125°C (K version).
2. Time until the voltage monitor 2 reset/interrupt request is generated since the voltage passes V_{det2}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.
4. Hold V_{det2} > V_{det1}.
5. When using the digital filter, its sampling time is added to t_d(V_{det2}-A). When using the voltage monitor 2 reset, maintain this time until V_{CC} = 2.0 V after the voltage passes V_{det2} when the power supply falls.

Table 5.20 Electrical Characteristics (3) [V_{CC} = 3 V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except XOUT	I _{OH} = -1 mA		V _{CC} - 0.5	—	V _{CC}	V
		XOUT	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except XOUT	I _{OL} = 1 mA		—	—	0.5	V
		XOUT	Drive capacity HIGH	I _{OL} = 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, KI0, KI1, KI2, KI3, TRAIO, RXD0, RXD1, CLK0, SSI, SCL, SDA, SSO			0.1	0.3	—	V
		RESET			0.1	0.4	—	V
I _{IH}	Input "H" current		V _I = 3 V, V _{CC} = 3 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 3 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 3 V		66	160	500	kΩ
R _{FXIN}	Feedback resistance	XIN			—	3.0	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode		2.0	—	—	V

NOTE:

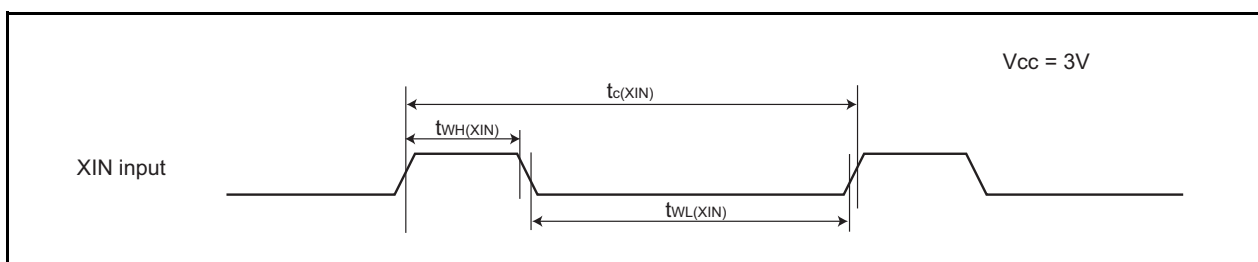
- V_{CC} = 2.7 to 3.3 V at T_{opr} = -40 to 85°C (D, J version) / -40 to 125°C (K version), f(XIN) = 10 MHz, unless otherwise specified.

**Table 5.21 Electrical Characteristics (4) [V_{CC} = 3 V]
(T_{opr} = -40 to 85°C (D, J version) / -40 to 125°C (K version), Unless Otherwise Specified.)**

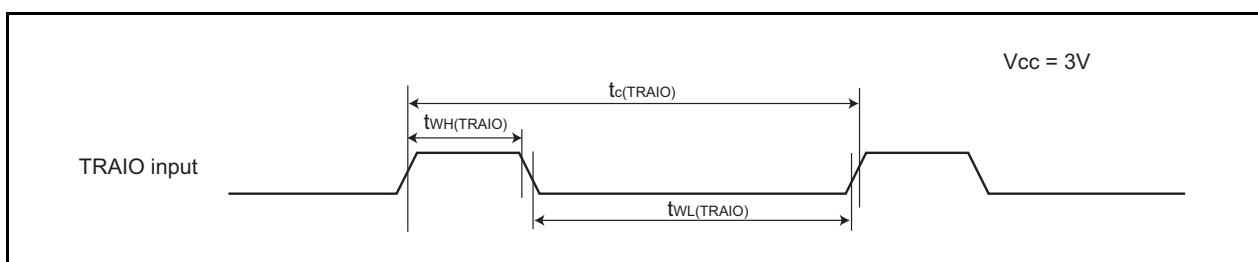
Symbol	Parameter	Condition	Standard			Unit	
			Min.	Typ.	Max.		
Icc	Power supply current (Vcc = 2.7 to 3.3 V) In single-chip mode, the output pins are open and other pins are Vss	High-clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	11.5	23.0	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	9.5	19.0	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	6.0	12.0	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	5.5	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4.5	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	6.3	12.6	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.1	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	145	290	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA20 = 0 VCA26 = VCA27 = 0	–	56	112	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA20 = 0 VCA26 = VCA27 = 0	–	35	70	μA
		Stop mode Topr = 25°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	0.7	3.0	μA
		Stop mode Topr = 85°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	1.1	–	μA
		Stop mode Topr = 125°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	3.8	–	μA

Timing Requirements (Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$) [$V_{CC} = 3\text{ V}$]**Table 5.22 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input "H" width	40	–	ns
$t_{WL(XIN)}$	XIN input "L" width	40	–	ns

**Figure 5.12 XIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.23 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input Cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	120	–	ns

**Figure 5.13 TRAIO Input Timing Diagram when $V_{CC} = 3\text{ V}$**

REVISION HISTORY	R8C/22 Group, R8C/23 Group Datasheet
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Rev.	Date	Description	
		Page	Summary
1.00	Oct 27, 2006	40	Table 5.15 Electrical Characteristics (1) [VCC = 5 V] → Table 5.14 Electrical Characteristics (1) [VCC = 5 V] revised. RAM Hold Voltage, Min.; “1.8” → “2.0” corrected.
		41	Table 5.16 Electrical Characteristics (2) [Vcc = 5 V] → Table 5.15 Electrical Characteristics (2) [Vcc = 5 V] revised. Wait mode revised.
		44	Table 5.21 Electrical Characteristics (3) [VCC = 3 V] → Table 5.20 Electrical Characteristics (3) [VCC = 3 V] revised. RAM hold voltage, Min.; “1.8” → “2.0” corrected.
		45	Table 5.22 Electrical Characteristics (4) [Vcc = 3 V] → Table 5.21 Electrical Characteristics (4) [Vcc = 3 V] revised. Wait mode revised.
1.10	Mar 16, 2007	–	D version products added. Relevant descriptions revised because of expanding products - Table 1.1 to 1.4 revised. - Figure 1.2 and 1.3 revised. - Figure 3.1 and 3.2 revised. - Table 5.1 to 5.15 revised. - Table 5.20 and 5.21 revised.
		15	Table 4.1 revised; 000Ah: “00XXX000b” → “00h”, 000Fh: “00011111b” → “00X11111b”
		42	Table 5.17 and Figure 5.9 revised; “INT1 input” deleted
		43	Table 5.19 and Figure 5.11 revised; “i = 0, 2, 3” → “i = 0 to 3”
		46	Table 5.23 and Figure 5.13 revised; “INT1 input” deleted
		47	Table 5.25 and Figure 5.15 revised; “i = 0, 2, 3” → “i = 0 to 3”
2.00	Aug 20, 2008	–	“RENESAS TECHNICAL UPDATE” reflected: TN-16C-A172A/E
		5, 6	Table 1.3, Table 1.4 revised Figure 1.2, Figure 1.3; ROM number “XXX” added
		13, 14	Figure 3.1, Figure 3.2; “Expanding area” deleted
		23	Table 4.9 135Fh Address “XXXX0000b” → “00h”
		28	Table 5.2; NOTE2 revised
		30	Table 5.4; NOTE2 and NOTE4 revised
		31	Table 5.5; NOTE2 and NOTE5 revised
		32	Table 5.6; “td(Vdet1-A)” added, NOTE5 added Table 5.7; “td(Vdet2-A)” and NOTE2 revised, NOTE5 added
		33	Table 5.8; “trth” and NOTE2 revised, Figure 5.3 revised

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